

## ESDULC5V0D9

### Description

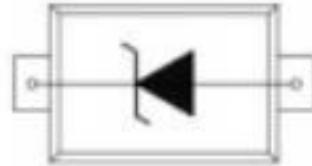
The ESDULC5V0D9 is designed to protect voltage sensitive components that require ultra-low capacitance from ESD and transient voltage events. Excellent clamping capability, low capacitance, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed and antenna line applications.



### Features

- Ultra low capacitance 0.5pF
- Stand-off voltage: 5V
- Low leakage current
- Package: SOD-923
- Low clamping voltage
- Response time is typically <1.0ns
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge: ±15kV
    - Contact discharge: ±8kV

### Functional Diagram



### Applications

- USB 2.0
- antenna line
- Data line

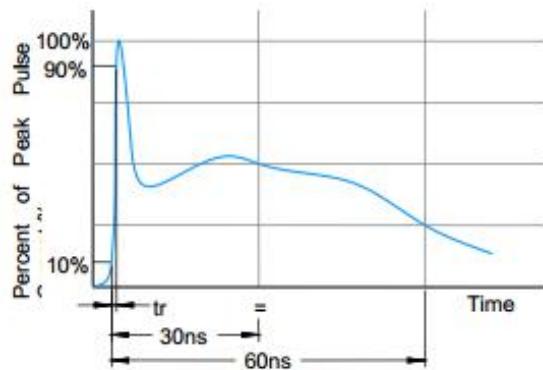
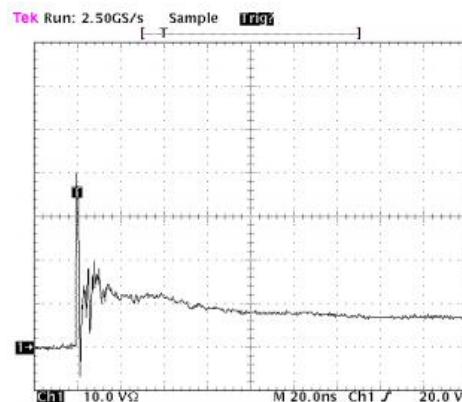
### Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

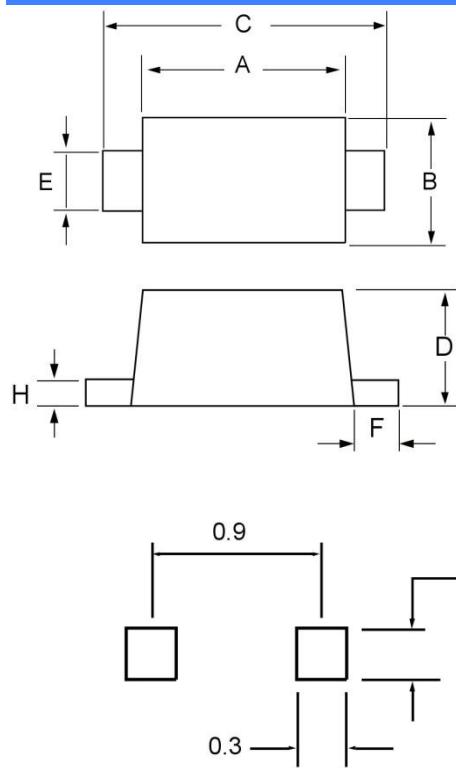
| Parameter                       | Symbol           | Value        | Unit  |
|---------------------------------|------------------|--------------|-------|
| Peak Pulse Power (8/20μs)       | P <sub>PP</sub>  | 150          | Watts |
| ESD per IEC 61000-4-2 (Air)     | V <sub>ESD</sub> | ±15          | KV    |
| ESD per IEC 61000-4-2 (Contact) |                  | ±10          | KV    |
| Lead Soldering Temperature      | T <sub>L</sub>   | 260 (10 sec) | °C    |
| Operating Temperature Range     | T <sub>J</sub>   | -55 to +125  | °C    |
| Storage Temperature Range       | T <sub>STJ</sub> | -55 to +150  | °C    |

## Electrical Characteristics (TA = 25 °C unless otherwise noted)

| Parameter                 | Symbol    | Conditions                       | Min. | Typ. | Max. | Units         |
|---------------------------|-----------|----------------------------------|------|------|------|---------------|
| Reverse Stand-off Voltage | $V_{RWM}$ |                                  |      |      | 5    | V             |
| Reverse Breakdown Voltage | $V_{BR}$  | $I_t = 1\text{mA}$               | 5.4  |      |      | V             |
| Reverse Leakage Current   | $I_R$     | $V_R = V_{RWM}$                  |      |      | 1    | $\mu\text{A}$ |
| Clamping Voltage          | $V_c$     | $@I_{PP}=1\text{A}$              |      |      | 9.8  | V             |
| Junction Capacitance      | $C_J$     | $V_R=0\text{V}, f = 1\text{MHz}$ |      |      | 0.9  | pF            |

## Characteristics Curves

 Figure 1- ESD Pulse Waveform  
 (according to IEC 61000-4-2)

 Figure 2- ESD VC Screenshot positive 8KV contact per  
 IEC 61000-4-2

 Figure3- Figure 2- ESD VC Screenshot negative 8KV  
 contact per IEC 61000-4-2


**PACKAGE OUTLINE DIMENSIONS in millimeters (inches) :**


| Dim | Inches |       | Millimeters |      |
|-----|--------|-------|-------------|------|
|     | MIN    | MAX   | MIN         | MAX  |
| A   | 0.030  | 0.033 | 0.75        | 0.85 |
| B   | 0.022  | 0.026 | 0.55        | 0.65 |
| C   | 0.037  | 0.041 | 0.95        | 1.05 |
| D   | 0.014  | 0.017 | 0.36        | 0.43 |
| E   | 0.006  | 0.010 | 0.15        | 0.25 |
| F   | 0.002  | 0.006 | 0.05        | 0.15 |
| H   | 0.003  | 0.007 | 0.07        | 0.17 |

**Mounting Pad Layout(mm)**
**Disclaimer**

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.